VIGON® UC 160

Water-based cleaning agent with high wetting ability for stencil underside wiping in printers

VIGON® UC 160 is a water-based cleaning agent specifically designed to remove solder paste from stencils in SMT printers. VIGON® UC 160 has an excellent wetting ability, which leads to an improved cleaning performance and thereby reduces smearing on the stencil underside significantly. This in turn prevents solder paste bridging on boards and ensures good and reliable printing results. VIGON® UC 160 is also an ideal replacement for Isopropanol due excellent health and safety characteristics, such as no flashpoint and a low VOC value.

Areas of application: Stencil and underside wipe cleaning		**Additional product information :**
Solder pastes (unsoldered)	++	**Technical Information sheet 3**: Overview regarding material compatibility

++ highly recommended, best results + recommended 0 possible - not recommended

Technical Centers - ① America, ② Europe, ③ Malaysia, ④ North-China, ⑤ South-China
Cleaning Process Solutions under Production Floor Conditions

Contact ZESTRON's Process Engineering Team for free-of-charge cleaning trials:
Phone: +49-841-635-26; Email: techsupport@zestron.com

Advantages compared to other cleaners:

- VIGON® UC 160 effectively removes the latest lead-free & lead-based solder pastes from stencils in underside wiping even out of fine pitch apertures. The cleaner is specifically suitable for print after wait.
- Provides excellent wetting ability on stencils and therefore increased cleaning performance, which significantly reduces smearing on the stencil underside. Thus bridging of solder paste on the boards can be avoided.
- Good delineation stability further ensures reduced solder balling.
- High operational safety and ideal replacement for Isopropanol due to excellent health and safety characteristics, no flash point, low VOC levels.
- VIGON® UC 160 has low odor.

Please refer to the material compatibility list (Technical Information 3) before using with plastic parts in the printer.